

WaferSense® Auto Vibration and Leveling Sensor™ (AVLS3)

Speed real-time vibration and leveling measurements.



Leveling



Vibration



Speed equipment qualification with wireless measurements

- Collect and display acceleration, vibration and leveling data.
- Use the AVLS3 with new CyberSpectrum™ software for real-time equipment diagnostics.
- See the effects of calibrations in real-time, speeding equipment alignment and set-up.

Shorten equipment maintenance cycles with thin and lightweight wafer-like form factor.

- Access more chambers with the thin 3.5mm form factor.
- Enable smooth wafer handling and improved vacuum chucking with the new Chemically Hardened Glass (CHG) substrate.
- Keep the process areas unexposed to the fab environment with vacuum compatible AVLS3.



Lower equipment maintenance expenses and enhance process uniformity with objective and reproducible data.

- Take the human element out of calibrating equipment with objective measurements for multiple applications in one.
- Make the right adjustments time after time.
- Receive early warning for impending equipment failures and optimize your preventative maintenance plans.

Semiconductor fabs and OEMs worldwide value the accuracy, precision and versatility of the WaferSense AVLS3 - The most efficient and effective wireless measurement device for leveling and vibration.

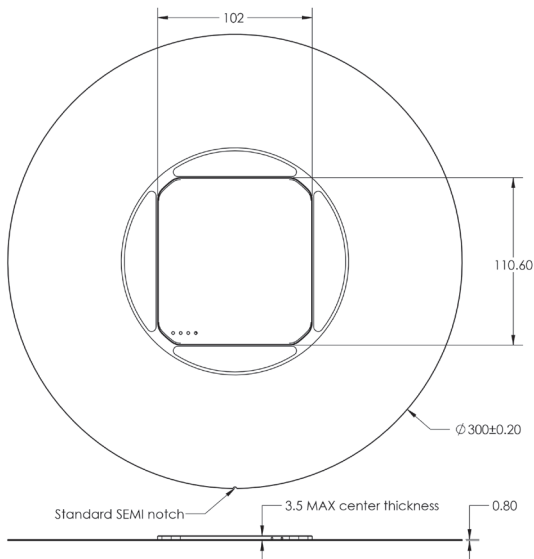


Save Time. Save Expense. Improve Yields.

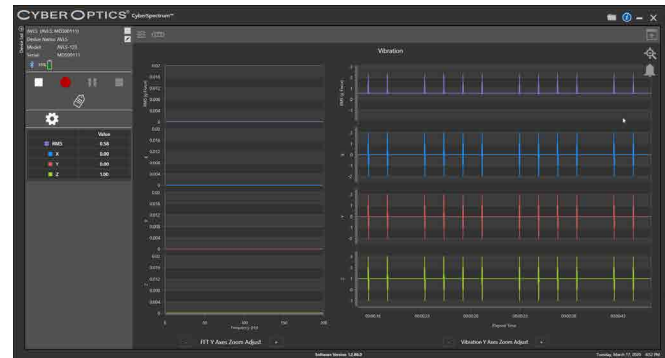
Features

Wireless, wafer-shaped and battery-powered	Available in 300mm
Easy-to-use software	CyberSpectrum software included CyberSpectrum: Displays real-time visual feedback. Digital readout allows more precise adjustment. Review functionality integrated; replays log file data for review and analysis
Highly accurate - leveling	Horizontal accuracy: +/-0.03 deg within +/- 7 deg from absolute. Horizontal resolution: +/-0.002deg within +/-14 deg. Reports inclination in two dimensions: x and y
Highly accurate - vibration	Reports accelerations in three directions: x, y, and z and RMS display allows quick, objective measurements. Operating range: +/- 4G.
Durable housing	Laminated chemically hardened glass
Lightweight	183 grams
Thin	3.5mm thick
Operating pressure	<10 ⁻⁶ to 760 torr
Operating temperature	20 to 60 degrees C
Battery-operation	>1 hour per charge. Inductive wireless charging and hands free operation.
WaferSense Link	Bluetooth, 2.4 GHz, USB 1.1, dimensions 92mm x 58mm x 28mm
Operating Systems	Windows 7, 8, 10
Product components	Auto Vibration and Leveling Sensor measurement device, charging clean box, carrying suitcase, USB communications link module and application software
Calibration	Factory recalibration recommended annually

Dimensions



CyberSpectrum™



Real-time data.



Contact CyberOptics today for your complimentary on-tool demonstration
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